



General Description

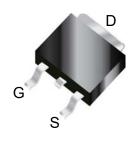
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

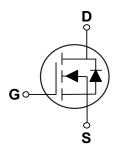
BV _{DSS}	R _{DS(ON)}	Ι _D
60 V	22 mΩ	42 A

Features

- $R_{DS(ON)} \leq 22 m \Omega @V_{GS} = 10 V$
- Fast Switching
- · Green Device Available

TO-263 Pin Configuration





Applications

- · Synchronous Rectification
- · DC/DC Converter

osolute Maximum Ratings T _C =25°C unless otherwise noted					
Symbol	Parameter	Rating	Units		
V_{DS}	Drain-Source Voltage	60	V		
V_{GS}	Gate-Source Voltage	±20	V		
I _D	Drain Current - Continuous (T _C =25°C)	42	Α		
I _{DM}	Drain Current - Pulsed (NOTE 1)	168	Α		
EAS	Single Pulse Avalanche Energy (NOTE 2)	51.2	mJ		
P _D	Power Dissipation (T _C =25°C)	61.8	W		
T _J	Operating Junction Temperature Range	-55 to 150	°C		
T _{STG}	Storage Temperature Range	-55 to 150	°C		
Marking Code		NG022			

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{ heta JC}$	Thermal Resistance Junction to Case	2.02	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60	1		V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A			22	mΩ
		V _{GS} =4.5V , I _D =10A			27	
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0		2.5	V
g _{fs}	Forward Transconductance	V _{DS} =10V , I _D =20A		50		S

Dynamic and switching Characteristics (NOTE 4)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			14.5		
Q_gs	Gate-Source Charge	V_{DS} =30V , V_{GS} =10V , I_{D} =20A		5.5		nC
Q_gd	Gate-Drain Charge			4		ı
$T_{d(on)}$	Turn-On Delay Time			12		
T _r	Rise Time	V_{DD} =30V , V_{GS} =10V , R_{G} =3 Ω , I_{D} =20A		32.8		nS
$T_{d(off)}$	Turn-Off Delay Time			17		113
T_f	Fall Time			9.5		
C_{iss}	Input Capacitance			1750		
C _{oss}	Output Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		90		pF
C_{rss}	Reverse Transfer Capacitance			74		
R_g	Gate Resistance	V_{GS} =0V , V_{DS} =0V , f=1MHz		2.4		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V, Force Current			42	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =20A			1.2	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. V_{DD} =50V, V_{GS} =10V, L=0.4mH, I_{AS} =16A.
- 3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 4. Guaranteed by design, not subject to production testing.





Characteristics Curves

FIG. 1-Drain Current

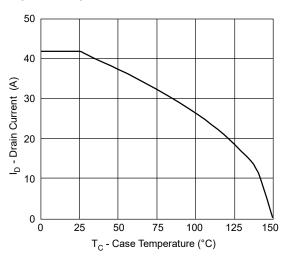


FIG. 2-Normalized $R_{DS(ON)}$ vs T_J

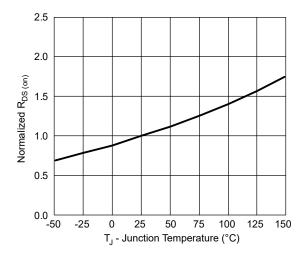


FIG. 5-Safe Operation Area

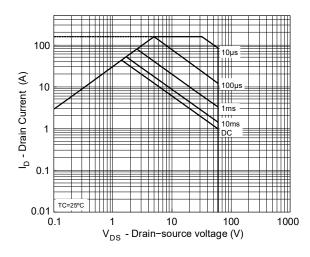


FIG. 2-Normalized $V_{GS(th)}$ vs T_J

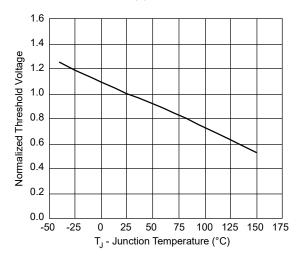
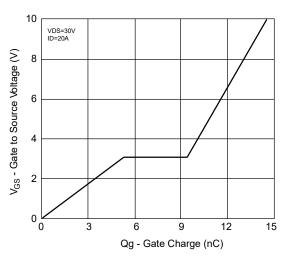


FIG. 4-Gate Charge Characteristics

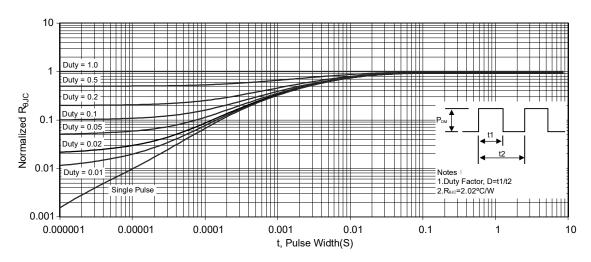




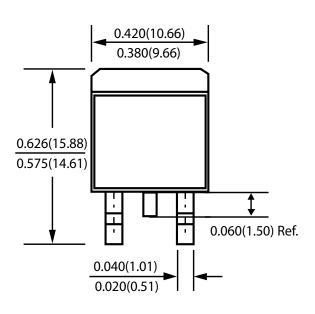


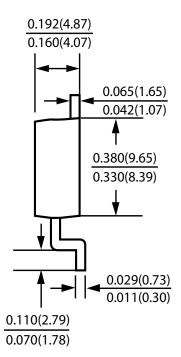
Characteristics Curves

FIG. 6-Normalized Transient Thermal Impedance



Package Outline Dimensions





TO-263Dimensions in inches and (millimeters)





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